METHOD OF FORMING BALL GRID ARRAY CONTACTS

ABSTRACT OF THE DISCLOSURE

The invention is a method for forming solder contacts (31) contacts areas (32) of ball grid array semiconductor devices (30). The semiconductor (30) is preheated and a plurality of solder forms are punched from a sheet of solder material directly onto contacts areas (32) on the semiconductor substrate. The substrate and solder forms are heated to reflowed the solder preform to form solder contacts (32) on the semiconductor substrate.

Figure 2